

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF:

Huan-Ping SU

GROUP:

SERIAL NO.:

EXAMINER:

FILED: Concurrently Herewith

FOR: METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES AND A CLAMPING DEVICE FOR MANUFACTURING A SEMICONDUCTOR PACKAGE

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAIL STOP PATENT APPLICATIONS

SIR:

This Preliminary Amendment is being filed concurrently with the filing of the above-identified new patent application

All necessary fees in connection with this matter should be deducted from deposit account No. 01-1944.